

APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR

Automotive Grade (AEC-Q200 Qualified)

Approved by customer : (signing or stamping here)	

SAMWHA CAPACITOR CO., LTD.									
Prepared by	Prepared by Checked by Approved by								
24-85	from	7/							

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< SPECIFICATION SUMMARY >								
SAMWHA Part no.		CQ:	1005C0G150J500NR					
Туре		MLCC for	r Automotive Application					
Items	Specification	Specification Unit Test Conditions						
Capacitance	15	pF	Testing Frequency : 1 ±0.1 MHz					
Capacitance Tolerance	± 5	%	Testing Voltage : 1 ±0.2 Vrms					
Dissipation Factor	Max. 0.14	%	Should be measured at 25℃.					
Insulation Resistance	Min. 100,000	MΩ	Should be measured with a DC voltage not exceeding rated voltage at 25℃ for 2 minutes of charging.					
	1.00 ±0.05	L (mm)	Capacitance Tolerance Code page 1/9					
Chip Size	0.50 ±0.05	W (mm)	Chip size page 2/9					
	0.50 ±0.05	T (mm)	Characteristics & Test Method page 3/9~6/9					

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	STANDARD	NO	SW - Q - 01A
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1. General Code

(1) Type Designation

CQ	1005	C0G	<u>150</u>	<u>J</u>	<u>500</u>	N	<u>R</u>	_
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Automotive Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	C0G	-55 to +125℃	±30 ppm/℃
	X7R	-55 to +125℃	±15%
Class II	X7S	-55 to +125℃	±22%
Class II	X7T	-55 to +125℃	+22% ~ -33%
	X6S	-55 to +105℃	±22%

4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) $104 = 100000 \, \text{pF}$

R denotes decimal

8R2 = 8.2 pF

5) Capacitance Tolerance Code

Code	Tolerance
В	± 0.1 pF
С	± 0.25 pF
D	± 0.5 pF
F	± 1.0 %

Code	Tolerance
G	± 2.0 %
J	± 5 %
K	± 10 %
M	± 20 %

6) Voltage Code

Code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Rated	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Voltage	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

N: Nickel-Tin Plate

A: Nickel-Tin Plate -> Soft Termination Type

8) Packing Code

R: 7" Reel Type, L: 13" Reel Type, B: Bulk Type

9) Thickness option

Thickne	Thickness (mm)		Thickne	Code	
t	Tolerance(±)	Code	t	Tolerance(±)	Code
0.50	0.05	Blank	1.35	0.20	Н
0.60	0.10	Α	1.60	0.20	Į
0.80	0.10	В	1.80	0.20	J
0.85	0.15	В	2.00	0.25	K
1.00	0.15	E	2.50	0.25	L
1.10	0.15	E	2.80	0.30	M
1.15	0.15	E	3.20	0.30	N
1.25	0.15	Е	5.00	0.40	0
1.30	0.20	E			

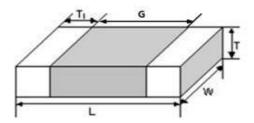
^{*3216} Size $\geq 2.2\mu F$ 100V \Rightarrow T : Tol ± 0.30

2. Temperature Characteristics

See Page 6/9 (No.21)

3. Constructions and Dimensions

(1) Dimensions



		Dimension							
Size Code	EIA Code	Length		Wie	dth	,	0(
		L	Tol(±)	W	Tol(±)	T1(min.)	G(min.)		
1005	0402	1.00	0.05	0.50	0.05	0.05	0.30		
1608	0603	1.60	0.15	0.80	0.10	0.10	0.50		
2012	0805	2.00	0.20	1.25	0.15	0.10	0.65		
3216	1206	3.20	0.30	1.60	0.20	0.15	1.00		
3225	1210	3.20	0.40	2.50	0.25	0.15	1.05		
4520	1808	4.50	0.40	2.00	0.25	0.20	1.50		
4532	1812	4.50	0.40	3.20	0.30	0.20	1.50		
5750	2220	5.70	0.50	5.00	0.40	0.30	1.85		

^{*3216} Size $\geq 2.2\mu F$ 100V \Rightarrow L, W : Tol ± 0.30 (Unit: mm)

(2) Construction of Termination



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Specifications and Test Methods (For Automotive Applications)

No	AEC-Q200		Spec	cification	Test Methods and Conditions					
NO.	l est Item		Class I	Class II	rest methods and conditions					
1	Pre-and Post- Electrical Tes			-	-					
		Appearance	No defects which may affect	performance						
2	High Temperature Exposure	Capacitance Change Q/D.F.	Within ±2.5% or ±0.25pF (Whichever is larger) 30pF min.: Q≥1000 30pF max.: Q≥400+20×C	Within ±10.0% (*Within ±12.5%) Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max.	Temperature: Max. operating temperature±3°C Maintenance Time: 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.					
	(Storage)		C: Nominal Capacitance (pF)	*0.2 max.	- Local of the state of the sta					
		I.R.	More than 10,000M Ω or 500 Ω (Whichever is smaller)	.·F (*50Ω·F)						
		Appearance	No defects which may affect	performance	Perform the 1000 cycles according to the four heat treatments					
		Capacitance Change Within ±2.5% or ±0.25pF (Whichever is larger) Within ±10.0%		Within ±10.0%	listed in the following table. Let sit for 24±2 hours at room temperature, then measure.					
3	Temperature	*	30pF min.:Q≥1000	Rated Voltage 16V min.: 0.05 max.	Step 1 2 3 4 Temp.(°C) -55+0/-3 25±2 125+3/-0 25±2					
	Cycle		30pF max.:Q ≥ 400+20xC C: Nominal Capacitance (pF)	10V: 0.075 max. *0.2 max.	Time(min) 15±3 1 15±3 1					
		I.R.	More than 10,000M Ω or 500 Ω (Whichever is smaller)	ι -P-F (*50Ω-F)	Initial measurement Perform the initial measurement according to Note 1 for Class I					
4	Destructive Physical Anal	ysis	No defects or abnormalities		Per EIA-469					
		Appearance	No defects which may affect	performance	Temperature : 25~65°C, Humidity : 80~98% Cycle Time : 24 hrs/cycle, 10 cycles					
		Capacitance Change	Within ±3.0% or±0.30pF (Whichever is larger)	Within ±12.5%	Let sit for 24±2 hours at room temperature, then measure.					
5	Moisture Resistance	Q/D.F.	30pF min.: Q≥350 10pF min. and 30pF max.: Q≥275+5/2×C 10pF max.: Q≥200+10×C C: Nominal Capacitance (pF) More than 10,000MΩ or 500Ω	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	70					
	I.R.		(Whichever is smaller)	(30221)	0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 Time(hrs)					
		Appearance	No defects which may affect	performance						
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Temperature: 85±3°C Humidity: 80~85%					
6	Biased Humidity	Q/D.F.	30pF min.: Q≥200 30pF max.: Q≥100+10/3xC C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Applied Voltage: Rated Voltage and 1.3+0.2/-0V Maintenance Time: 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.					
	I.R.		More than 1,000M Ω or 50 Ω ·F (Whichever is smaller)	(*5Ω·F)	The charge/discharge current is less than 50mA.					
		Appearance	No defects which may affect	performance	T					
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Temperature : Max. operating temperature±3°C Applied Voltage : Rated Voltage × 200% (*150%) Maintenance Time : 1000+48/-0 hrs					
7	Operational Life	Q/D.F.	30pF min.:Q≥350 10pF min. and 30pF max.: Q≥275+5/2×C 10pF max.: Q≥200+10×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Let sit for 24±2 hours at room temperature, then measure. The charge/discharge current is less than 50mA. Initial Measurement for Class II Applied 200% of the rated voltage for one hour at 125±3°C. Remove and let sit for 24±2 hours at room temperature, then					
	I.R.		More than 1,000M Ω or 50 Ω ·F (Whichever is smaller)	(*5Ω·F)	measure.					

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Specifications and Test Methods (For Automotive Application)

	AEC-Q200		Specif	ication		Test Methods and Conditions				
No.		t Item Class Class		II	l est Methods and Conditions					
8	External Visua	al	No defects or abnormalities			Visual inspection				
9	Physical Dime	ension	Within the specified dimensions			Using calipers				
		Appearance	No defects which may affect performance							
		Capacitance Change	Within the specified tolerance							
10	Resistance to Solvents	Q/D.F.	30pF min.: Q≥1000 30pF max.: Q≥400+20xC C: Nominal Capacitance (pF)	16V: (10V: (*0.125 max.	0.025 max. 0.03 max. 0.035 max. 0.05 max.	Per MIL-STD-202 Method 215				
		I.R. More than 10,000M Ω or 500 Ω ·F (*50 Ω ·F) (Whichever is smaller)								
		Appearance	No defects which may affect p	erformance						
		Capacitance Change	Within the specified tolerance			Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks)				
11	Mechanical Shock	echanical 30pF min.:Q≥1000 Rated Voltage 50V: 0.025 max. 25V: 0.03 max.		0.03 max. 0.035 max.	Test Pulse Wave form : Half-sine Duration : 0.5ms Peak value : 1,500G					
		I.R.	More than $10,000M\Omega$ or 500Ω -F (Whichever is smaller)			Velocity change : 4.7m/s				
		Appearance	No defects or abnormalities							
		Capacitance Change Within the specified tolerance				The specimens should be subjected to a simple harmonic motion				
12	Vibration	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V: (0.025 max. 0.03 max. 0.035 max. 0.05 max.	having a total amplitude of 1.5mm. The entire frequency range of 10 to 2,000 Hz and return to 10 Hz should be traversed in 20 minutes. This cycle should be performed 12 times in each of three mutually perpendicular directions (total of 36 times).				
		I.R.	More than 10,000M Ω or 500 Ω -F (Whichever is smaller)							
		Appearance	No defects which may affect p	erformance						
		Capacitance Change	Within the specified tolerance			Temperature (Eutectic solder solution) : 260±5℃				
13	Resistance to Soldering Heat	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	Rated Voltage 50V: 0.025 max. 25V: 0.03 max. 16V: 0.035 max. 10V: 0.05 max.		Dipping Time: 10±1s Let sit for 24±2 hours at room temperature, then measure. Initial measurement Perform the initial measurement according to Note 1 for Class II				
		I.R.	More than 10,000M Ω or 500 Ω -F (Whichever is smaller)	ore than 10,000MΩ or 500Ω·F (*50Ω·F)		-				
		Appearance	No defects which may affect p	efects which may affect performance		Perform the 300 cycles according to the two heat treatments listed				
		Capacitance Within ±2.5% or ±0.25pF Change (Whichever is larger) Within ±15.0%			in the following table. Transfer Time: 20sec. max.					
14	Thermal Shock	Q/D.F.	30pF min.:Q≥1000 30pF max.:Q≥400+20xC C: Nominal Capacitance (pF)	16V: (0.025 max. 0.03 max. 0.035 max. 0.05 max.	Let sit for 24±2 hours at room temperature, then measure. Step 1 2 Temp.(°C) -55+0/-3 125+3/-0 Time(min.) 15±3 15±3				
		I.R.	More than 10,000M Ω or 500 Ω -F (Whichever is smaller)			Initial measurement Perform the initial measurement according to Note 1 for Class II.				

Specifications and Test Methods (For Automotive Application)

ΤĖ			· · · · · · · · · · · · · · · · · · ·	ication	,						
No.	AEC-Q200 Test Item		Class	Class II	Tes	st Methods a	nd Condition	ons			
		Appearance	No defects which may affect pe	erformance							
		Capacitance	Within the specified tolerance								
		Change		Rated Voltage 50V: 0.025 max.	-						
	F0D		30pF min.:Q≧1000	25V: 0.03 max.	D 450 0000						
15	ESD	Q/D.F.	30pF max.:Q≧400+20×C	16V: 0.035 max.	Per AEC-Q200	-002					
			C: Nominal Capacitance (pF)	10V: 0.05 max.							
				*0.125 max.							
		I.R.	More than $10,000M\Omega$ or 500Ω ·F	(*50Ω·F)							
			(Whichever is smaller)		(a) Droboot at 1	155°C for 4 bours	and than immar	as the conscitor			
						155 $℃$ for 4 hours, and ros					
						5+0/-0.5 seconds a		cutcotto soluci			
						g for 8 hours, and t		ne capacitor in a			
16	Solderability		95% of the terminations is to be s	oldered evenly and continuously.	1, ,	ethanol and rosin. In					
	,			,	solution for s	5+0/-0.5 seconds a	at 235±5℃.				
					(c) Steam aging	g for 8 hours, and t	hen immerse th	ne capacitor in a			
					solution of e	ethanol and rosin. In	mmerse in eute	ctic solder			
					solution for	120±5 seconds at 2	260±5℃.				
		Appearance	No defects or abnormalities			ce/Q/D.F. should be		25℃ at the			
		Capacitance			l	voltage shown in th					
		Change	Within the specified tolerance		Class	Capacitance (C)	Frequency	Voltage			
					Class I	C<1000pF C≥1000pF	1±0.1MHz 1±0.1kHz	0.5~5Vrms 1±0.2Vrms			
						C≤10µF	1±0.1kHz	0.5~1.0Vrms			
				Rated Voltage 50V: 0.025 max.	Class II	C>10µF	120±24Hz	0.5±0.1Vrms			
			30pF min.:Q≧1000	25V: 0.03 max.	· Initial measurement						
	Electrical	Q/D.F.	30pF max.:Q ≥ 400+20×C	16V: 0.035 max.	Perform the initial measurement						
17	Characteriza-		C: Nominal Capacitance (pF)	10V: 0.05 max.	_	o Note1 for Clas	SS II				
	tion	ı		*0.125 max.	· Measurement after test Take it out and set it for 24±2 hours (Class II)						
					then measur		(0	,			
			More than $100,000M\Omega$ or $1,000\Omega$ ·F	More than 10,000MΩ 500Ω-F							
		I.R. at 25℃	(Whichever is smaller)	(*50Ω·F) (Whichever is smaller)	Should be mea	sured with a DC vo	oltage not exce	edina rated			
		I.R. at	More than $10,000M\Omega$ or 100Ω -F	More than 1.000MΩ or 10Ω·F	Should be measured with a DC voltage not exceeding rated voltage at 25°C and 125°C for 2 minutes of charging.						
		125℃	(Whichever is smaller)	(*1Ω·F) (Whichever is smaller)			-				
		Dielectric			Applied 250% of the rated voltage for 1~5 seconds						
		Strength	No dielectric breakdown or mecha	anical breakdown	The charge/discharge current is less than 50mA.						
					Apply a force in	the direction show	vn in the followi	ng figure for			
				,	60±5 seconds.						
		Appearance	No defects which may affect pe	ertormance	Support	Solder Chip	Printed circu	it board before testing			
					4	Vanitary.					
					1 1	45±2	45±2	Y			
					1=-						
18	Board Flex					20	Probe to exert	bending force			
					1	2-1-240	Speed: 1.0	mm/s			
			Within ±5.0% or ±0.5pF	Within the specified tolerance	1.6	Radius 340	ν				
		Change	(Whichever is larger)	· · · · · · · · · · · · · · · · · · ·	7	Noning to the second		0 0			
					Printed circuit bos	ard under test		Displacement			
								Displacement —			
					Flexure for Class I: 3mm max.						
-		Annograns	No defeate which may offer to	or formance.		Class II: 2mm max					
19	Terminal	• • • • • • • • • • • • • • • • • • • •	No defects which may affect pe	er rorillance		ce in parallel with tl EIA:0603) size	ne test jig for 60	J±1 seconds.			
19	Strength	1 -	Within ±5.0% or ±0.5pF	Within the specified tolerance	1	EIA:0603) size EIA:0402) size					
<u> </u>		Change	(Whichever is larger)		2141011003(E	_,, 1.0-102/ 3126					

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Specifications and Test Methods (For Automotive Application)

Test		The chip endure follow	wing force.		Class	1e	st wet	nous a	na Con	aitions	5			
3eam Load T∈	est							Test Methods and Conditions						
Beam Load Te	est	Chip Length	Thickne	The chip endure following force.					Apply a force as shown in the following figure.					
Beam Load Te	est		Chip Length Thickne		Force	(i) Chip Length		,	ii) Chip Le	•				
Beam Load Te	est	2.5mm max.	T≤0.	5mm	8N	Beam Speed	d : 0.5mr	n/s	Beam S	speed : 2.	omm/s			
		2.5mm max.	T>0.5mm		20N	ļ								
		3.2mm min.	T<1.2	25mm	15N		Iro	n Board						
		3.211111 11111.	T≥1	.25	54.5N	0 0								
Capacitance Femperature Characteris- ics	Capacitance Change Temperature Coefficient Capacitance Drift	0±30 ppm/°C		X7R: Wit X7S: Witl X6S: Witl X7T: Witl	hin ±22%	(i) Class I The temperature coefficient is determined using the capacitance measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through 5, the capacitance should be within the specified tolerance for the temperature coefficient. The capacitance drift is calculated by dividing the differences between the maximum and minimum measured values in steps 1, 3 and 5 by the capacitance value in step 3. Step 1 2 3 4 5 Temp.(°C) 25±2 -55±3 25±2 125±3 25±2 (ii) Class II The ranges of capacitance change compared with the 25°C value over the temperature range from -55°C to 125°C.								
Γe Cł	emperature naracteris-	coefficient Coeffi	coefficient 0±30 ppm/°C Coefficient 0±30 ppm/°C Capacitance Demonstrates Capacitance Within ±0.2% or ±0.05	coefficient O±30 ppm/°C Coefficient O±30 ppm/°C Capacitance D±30 ppm/°C Capacitance D±30 ppm/°C Within ±0.2% or ±0.05pF	Temperature Coefficient 0±30 ppm/°C capacitance Capacitance Within ±0.2% or ±0.05pF	Temperature Coefficient 0±30 ppm/°C capacitance Capacitance Within ±0.2% or ±0.05pF	Temperature Coefficient Temperature Coefficient 0±30 ppm/°C Step Temp.(°C) (ii) Class II The ranges of cover the temperature (Whichever is larger)	Temperature Coefficient Temperature Coefficient 0±30 ppm/°C Step 1 Temp.(°C) 25±2 (ii) Class II The capacitance drift is between the maximum at 1, 3 and 5 by the capacitance of t	Temperature Coefficient O±30 ppm/°C O±30 ppm/°C Temperature Coefficient O±30 ppm/°C O±30 ppm/°C O±30 ppm/°C Step 1 2 Temp.(°C) 25±2 -55±3 (ii) Class II The capacitance drift is calculated between the maximum and minim 1, 3 and 5 by the capacitance value of the	Temperature Coefficient O±30 ppm/°C Temperature Coefficient O±30 ppm/°C Step 1 2 3 Tempe.(°C) 25±2 -55±3 25±2 (ii) Class II The ranges of capacitance change compare over the temperature solution over the temperature over the temperature solution over the temperature over the temperature solution of the	Temperature Coefficient O±30 ppm/°C Temperature Coefficient O±30 ppm/°C O±30 ppm/°C The capacitance drift is calculated by dividing the difference of the temperature between the maximum and minimum measured value 1, 3 and 5 by the capacitance value in step 3. Step 1 2 3 4 Temp.(°C) 25±2 -55±3 25±2 125±3 (ii) Class II The capacitance value in step 3. Step 1 2 3 4 Temp.(°C) 25±2 -55±3 25±2 125±3 (iii) Class II The ranges of capacitance change compared with the over the temperature range from -55 °C to 125 °C.			

In the case of "*" is specifications for "Thin Layer Large Capacitance Type"

Note 1. Initial Measurement for Class II

Perform a heat treatment at 150+0/-10°C for one hour, and then let sit for 24±2 hours at room temperature, then measure.

(Unit: mm)

Packing

- (1) Bulk Packing
 - 1 1000 pcs per polybag
 - ② 5 polybags per inner box
 - 3 10 inner boxes per out box
- (2) Reel Packing
 - ① 8~10 reels per inner box
 - 2 6 inner boxes per out box
- (3) Reel Dimensions



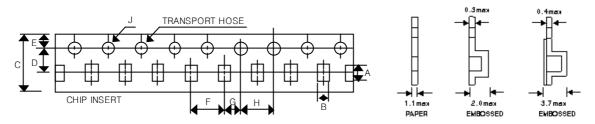


Mark	Size Code	EIA Code	Α	В	С	D	Е	w
7 " Reel	1005~3225	0402~1210	Ф178±2	Ф 50Min	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5
7 11001	4520~4532	1808~1812	Ф180+0,-3	Ф60-0,+1	Ф13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " Reel	1005~3225	0402~1210	Ф330±2	Φ 70Min	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5

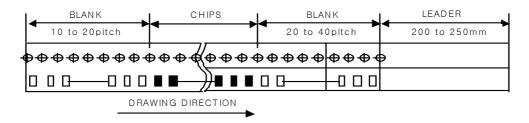
(4) Number of Package

Size Code	EIA Code	7"	13"		
Size Code	EIA Code	Quantity(pcs)/Reel	Quantity(pcs)/Reel		
1005	0402	10,000	50,000		
1608	0603	4,000	15,000		
2012	0805	3,000 ~ 4,000	8,000 ~ 15,000		
3216	1206	2,000 ~ 4,000	6,000 ~ 10,000		
3225	1210	1,000 ~ 3,000	4,000 ~ 10,000		
4520	1808	1,500 ~ 3,000	-		
4532	1812	500 ~ 1,000	1,500 ~ 5,000		

(5) Tape Dimensions



Size Code	EIA Code	А	В	С	D	E	F	G	Н	J
1005	0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
1608	0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
2012	0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3216	1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3225	1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4520	1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4532	1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



Caution

► Storage Condition

When solderability is considered, capacitor are recommended to be used in 12 months.

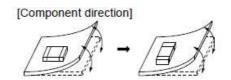
(1) Temperature: 25° C ± 10° C

(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials Never use materials mentioned below in MLCC products regulated this document. Pb, Cd, Hg, Cr⁺⁶, PBB(Polybrominated biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos

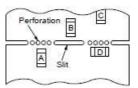
▶ Mounting Position

Choose a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.



Locate chip horizontal to the direction in which stress acts.

[Chip Mounting Close to Board Separation Point]



Chip arrangement Worst A-C- (B, D) Best

► Reflow Soldering

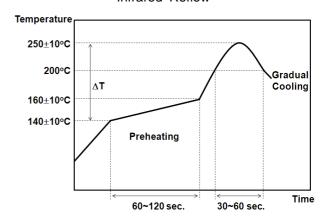
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference($\triangle T$) within the range recommended in Table 1.

Table 1

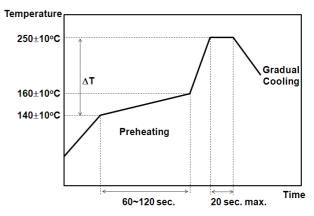
Size code (EIA Code)	Temperature Difference
1005~3216 (0402~1206)	△T≤190℃
3225 (1210)	△T≤130°C

Recommended Reflow Soldering Profile for Lead Free Solder

Infrared Reflow



Vapor Reflow



Note

▶ 'Aging'/'De-aging' behavior of high dielectric constant type MLCCs (Typically represented by X7R temperature characteristic of which main composition is BaTiO₃)

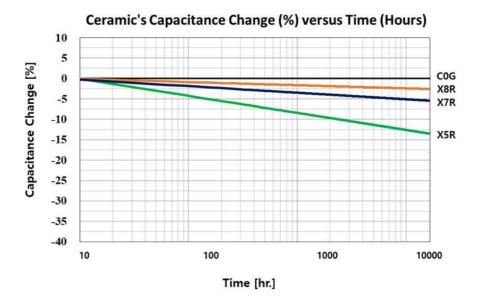
'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k log 10 t)$$

where,

Ct : Capacitance value, t hours after the start of 'aging' C₂₄ : Capacitance value, 24 hours after its manufacture : Aging constant (capacitance decrease per decade-hour)

: time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately 120°C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at 150°C for about 1 hour.